



Title of Change:	Final PCN for wafer fabrication site addition of ON Semiconductor Niigata Co., Ltd. In Niigata, Japan (Group JF)		
Proposed first ship date:	12 August 2015		
Contact information:	Contact your local ON Semiconductor Sales Office or <Yasuhiro.Igarashi@onsemi.com>		
Samples:	Contact your local ON Semiconductor Sales Office		
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or <Kazutoshi.Kitazume@onsemi.com>.		
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <PCN.Support@onsemi.com>.		
Change Part Identification:	Affected products will be identified with date code.		
Change category(s):	<input checked="" type="checkbox"/> Wafer Fab Change <input checked="" type="checkbox"/> Manufacturing Site Change/Addition <input type="checkbox"/> Product specific change <input type="checkbox"/> Assembly Change <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Test Change <input type="checkbox"/> Material Change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____		
Sites Affected:	<u>Site 1</u>	<u>Site 2</u>	
<input type="checkbox"/> All site(s) <input type="checkbox"/> not applicable <input checked="" type="checkbox"/> ON Semiconductor site(s) : <input type="checkbox"/> External Foundry/Subcon site(s):	ON Niigata, Japan		
Description and Purpose:			
<p>This is a Final Process Change Notification to announce the addition of a new wafer fabrication site for the device covered in this notice. Device formerly manufactured at the Manufacturers UMC will be manufactured at ON Semiconductor Niigata Co., Ltd. (OSNC) following the expiration of this notice. OSNC located in Niigata, Japan has obtained ISO9001 certification.</p> <p>The product design and electrical specifications will remain identical. A full electrical characterization over the temperature range will be performed to check the device functionality and electrical specifications. Qualification tests are designed to show that the reliability of transferred devices will continue to meet or exceed ON Semiconductor standards.</p>			
Reliability Data Summary:			
Test:	Conditions:	Interval:	Results:
Steady State Operating Life	Tj=150degC	1000 hrs	Pass
High Temperature Reverse Bias	Ta=150degC,VDSS =max	1000 hrs	Pass
Temp Humidity Storage	Ta=85degC, RH=85%	1000 hrs	Pass
Temperature Cycle	Ta=-55degC to 150degC 30min each	100 cycles	Pass
Pressure Cooker	Ta=121degC,2.03x105Pa,100%	50 hrs	Pass
High Temperature Storage	Ta=150degC	1000 hrs	Pass
Resistance to Soldering heat(Reflow)	Solder Temp.:260degC±5degC	10 s	Pass
Solderability	Solder Temp.: 245degC±5degC	5 s	Pass
Electrical Characteristic Summary:			
There is no change in the electrical performance. Datasheet specifications remain unchanged.			
List of affected Standard Parts:			
ATP106-TL-H			